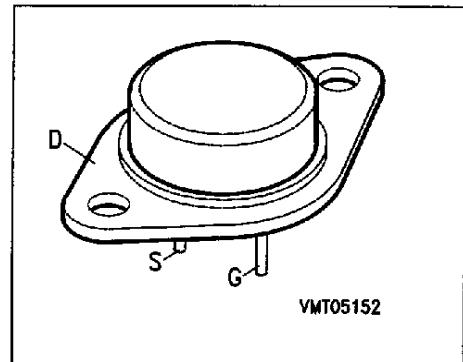


SIPMOS® Power Transistor

BUZ 24

- N channel
- Enhancement mode
- Avalanche-rated



Type	V_{DS}	I_D	$R_{DS(on)}$	Package ¹⁾	Ordering Code
BUZ 24	100 V	32 A	0.06 Ω	TO-204 AE	C67078-S1003-A2

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current, $T_C = 27^\circ\text{C}$	I_D	32	A
Pulsed drain current, $T_C = 25^\circ\text{C}$	$I_{D\text{ puls}}$	128	
Avalanche current, limited by $T_{j\text{ max}}$	I_{AR}	32	
Avalanche energy, periodic limited by $T_{j\text{ (max)}}$	E_{AR}	15	
Avalanche energy, single pulse $I_D = 32 \text{ A}$, $V_{DD} = 25 \text{ V}$, $R_{GS} = 25 \Omega$ $L = 322 \mu\text{H}$, $T_j = 25^\circ\text{C}$	E_{AS}	220	mJ
Gate-source voltage	V_{GS}	± 20	V
Power dissipation, $T_C = 25^\circ\text{C}$	P_{tot}	125	W
Operating and storage temperature range	T_j , T_{stg}	-55 ... +150	°C

Thermal resistance, chip-case	$R_{th\text{ JC}}$	≤ 1.0	K/W
DIN humidity category, DIN 40 040	-	C	-
IEC climatic category, DIN IEC 68-1	-	55/150/56	

1) See chapter Package Outlines.

Electrical Characteristicsat $T_j = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static characteristics

Drain-source breakdown voltage $V_{GS} = 0 \text{ V}, I_D = 0.25 \text{ mA}$	$V_{(\text{BR})\text{DSS}}$	100	—	—	V
Gate threshold voltage $V_{GS} = V_{DS}, I_D = 1 \text{ mA}$	$V_{GS(\text{th})}$	2.1	3.0	4.0	
Zero gate voltage drain current $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$ $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	I_{DSS}	—	0.1	1.0	μA
—	—	—	10	100	
Gate-source leakage current $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	I_{GSS}	—	10	100	nA
Drain-source on-resistance $V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	$R_{DS(\text{on})}$	—	0.05	0.06	Ω

Dynamic characteristics

Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max}}, I_D = 20 \text{ A}$	g_{fs}	10	17	—	S
Input capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{iss}	—	1400	1850	pF
Output capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{oss}	—	450	700	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	C_{rss}	—	230	370	
Turn-on time t_{on} , ($t_{\text{on}} = t_{d(\text{on})} + t_r$) $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}, R_{GS} = 50 \Omega$	$t_{d(\text{on})}$	—	30	45	ns
	t_r	—	80	125	
Turn-off time t_{off} , ($t_{\text{off}} = t_{d(\text{off})} + t_f$) $V_{DD} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}, R_{GS} = 50 \Omega$	$t_{d(\text{off})}$	—	250	320	
	t_f	—	120	160	

Electrical Characteristics (cont'd)at $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

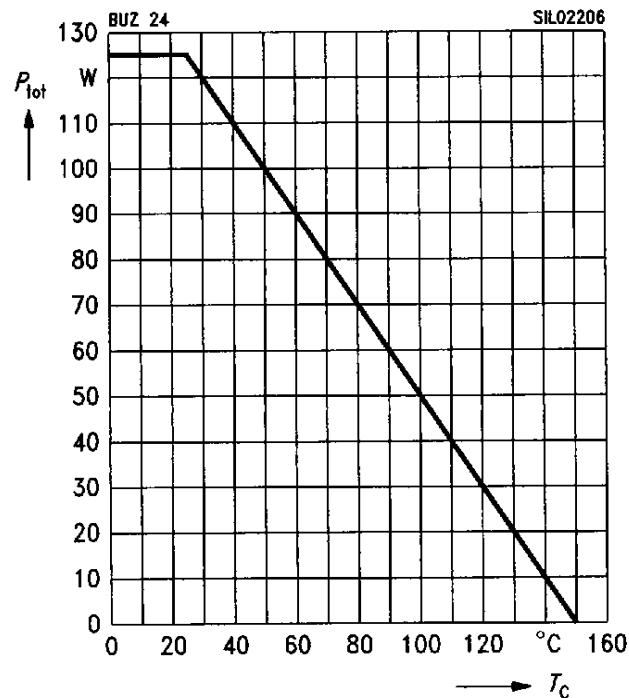
Reverse diode

Continuous reverse drain current $T_C = 25^\circ\text{C}$	I_S	—	—	32	A
Pulsed reverse drain current $T_C = 25^\circ\text{C}$	I_{SM}	—	—	128	
Diode forward on-voltage $I_S = 64 \text{ A}, V_{GS} = 0 \text{ V}$	V_{SD}	—	1.4	1.7	V
Reverse recovery time $V_R = 30 \text{ V}, I_F = I_S, di_F / dt = 100 \text{ A}/\mu\text{s}$	t_{rr}	—	130	—	ns
Reverse recovery charge $V_R = 30 \text{ V}, I_F = I_S, di_F / dt = 100 \text{ A}/\mu\text{s}$	Q_{rr}	—	0.7	—	μC

Characteristics at $T_j = 25^\circ\text{C}$, unless otherwise specified.

Total power dissipation

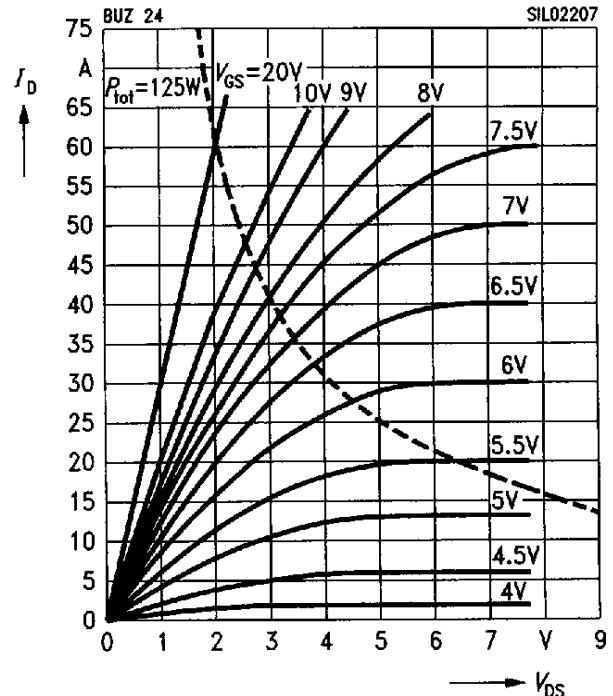
$$P_{\text{tot}} = f(T_c)$$



Typ. output characteristics

$$I_D = f(V_{DS})$$

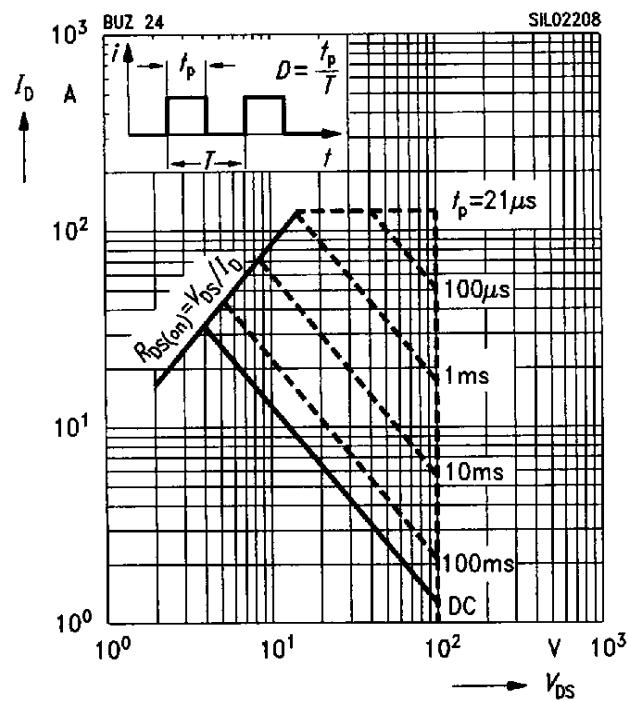
parameter: $t_p = 80 \mu\text{s}$



Safe operating area

$$I_D = f(V_{DS})$$

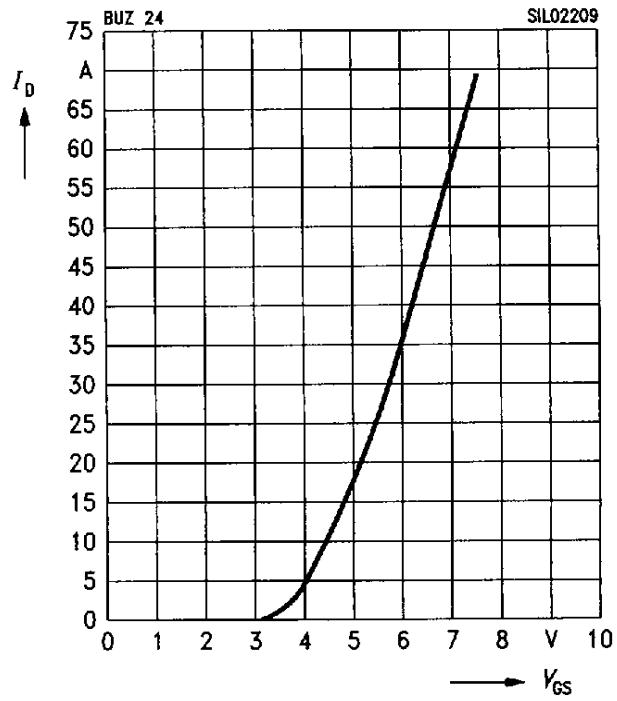
parameter: $D = 0.01$, $T_c = 25^\circ\text{C}$



Typ. transfer characteristics

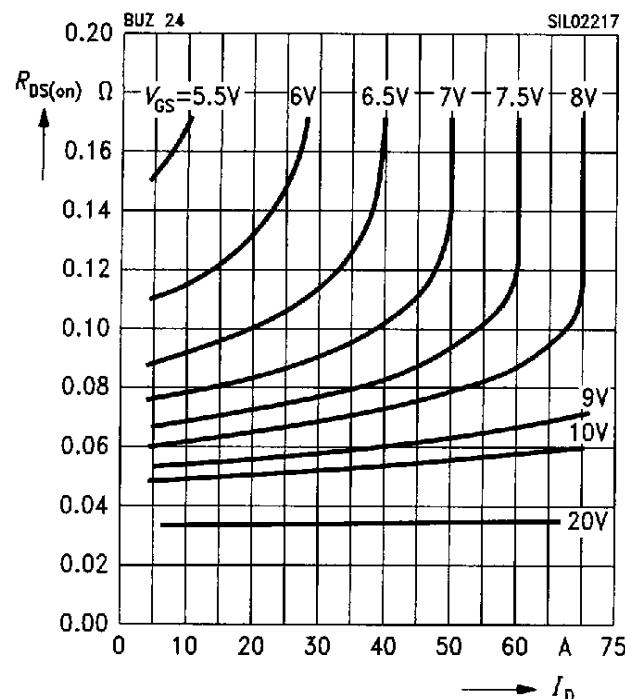
$$I_D = f(V_{GS})$$

parameter: $t_p = 80 \mu\text{s}$, $V_{DS} = 25 \text{ V}$

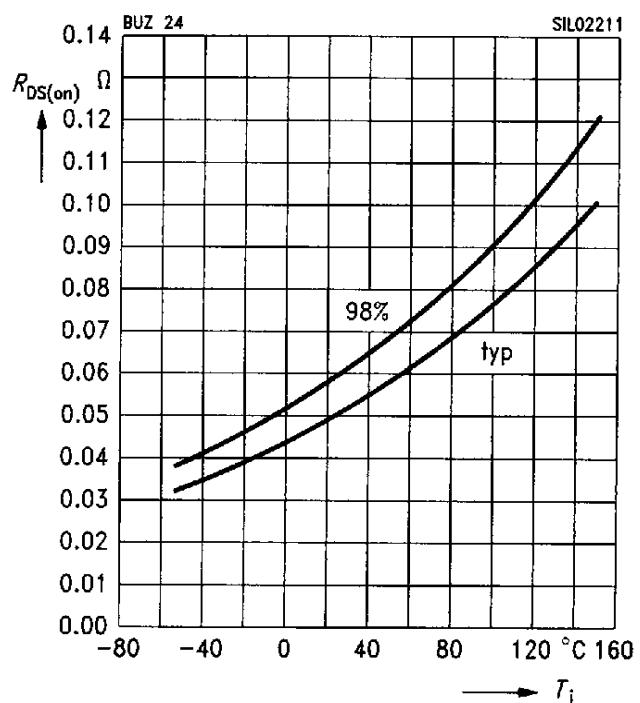


Typ. drain-source on-resistance

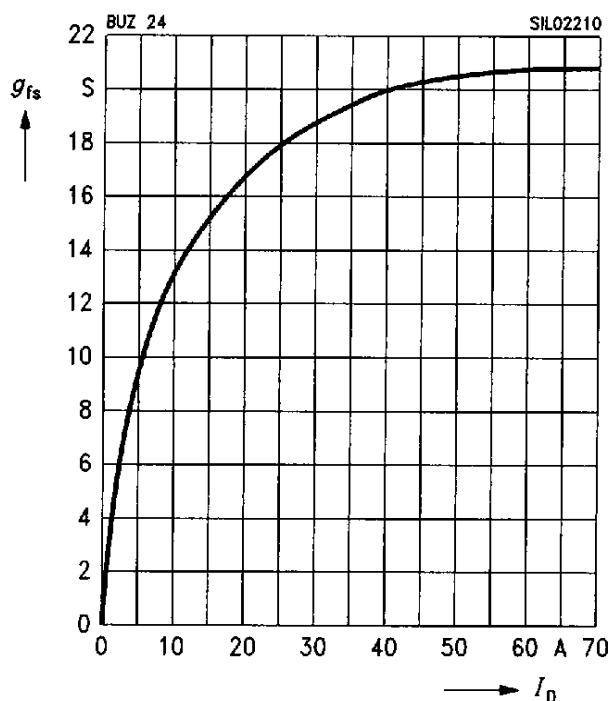
$$R_{DS(on)} = f(I_D)$$

parameter: V_{GS} **Drain-source on-resistance**

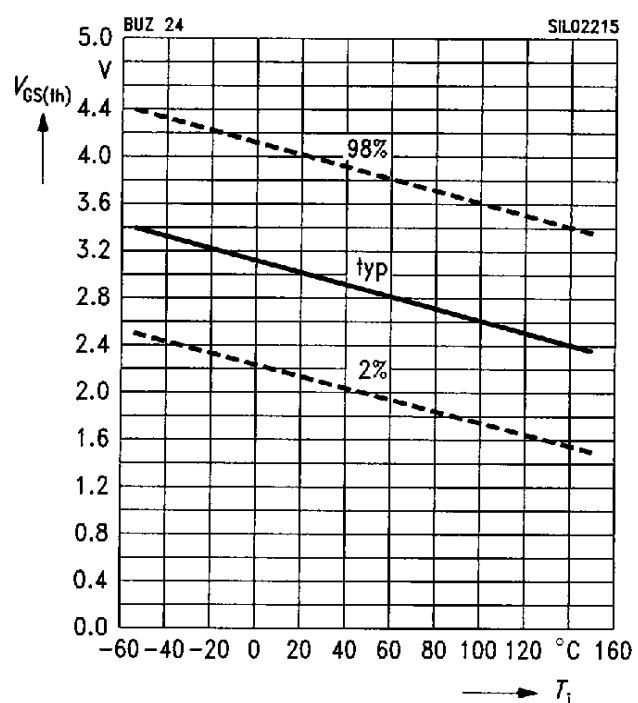
$$R_{DS(on)} = f(T_j)$$

parameter: $I_D = 20 A, V_{GS} = 10 V$, (spread)**Typ. forward transconductance**

$$g_{fs} = f(I_D)$$

parameter: $t_p = 80 \mu s$ **Gate threshold voltage**

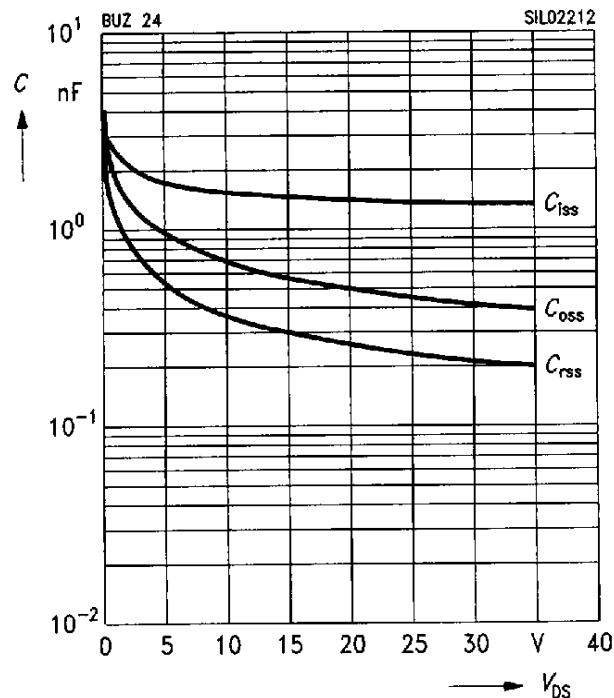
$$V_{GS(th)} = f(T_j)$$

parameter: $V_{GS} = V_{DS}, I_D = 1 mA$, (spread)

Typ. capacitances

$$C = f(V_{DS})$$

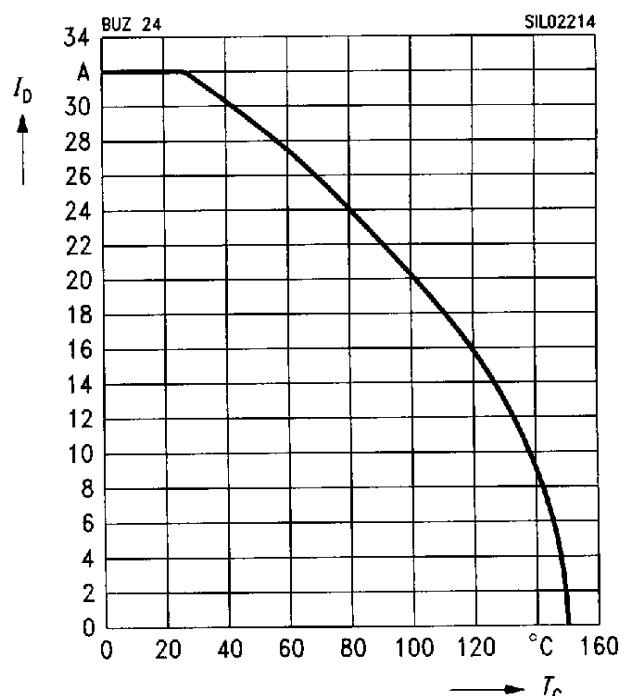
parameter: $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$



Drain current

$$I_D = f(T_C)$$

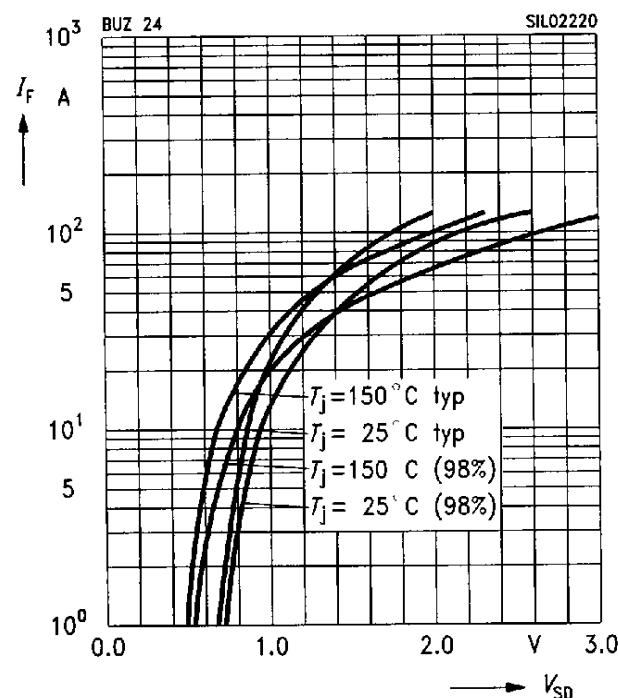
parameter: $V_{GS} \geq 10 \text{ V}$



Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

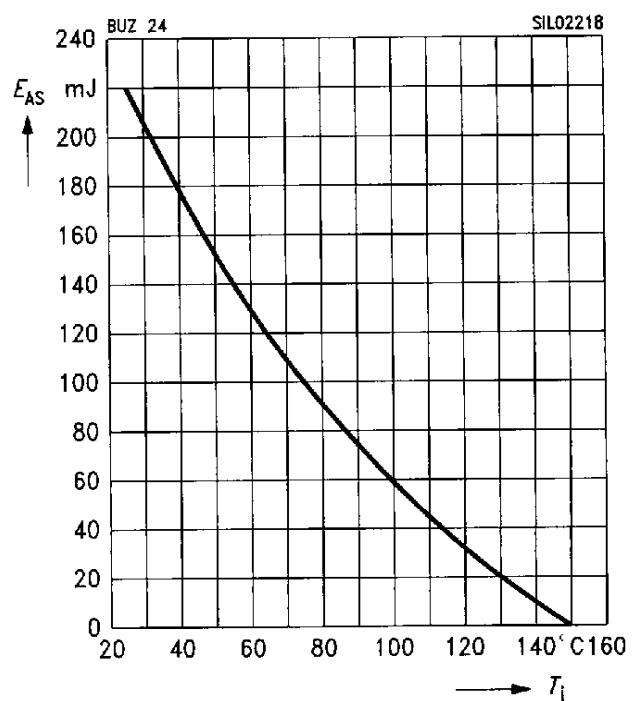
parameter: T_j , $t_p = 80 \mu\text{s}$, (spread)



Avalanche energy $E_{AS} = f(T)$

parameter: $I_D = 32 \text{ A}$, $V_{DD} = 25 \text{ V}$

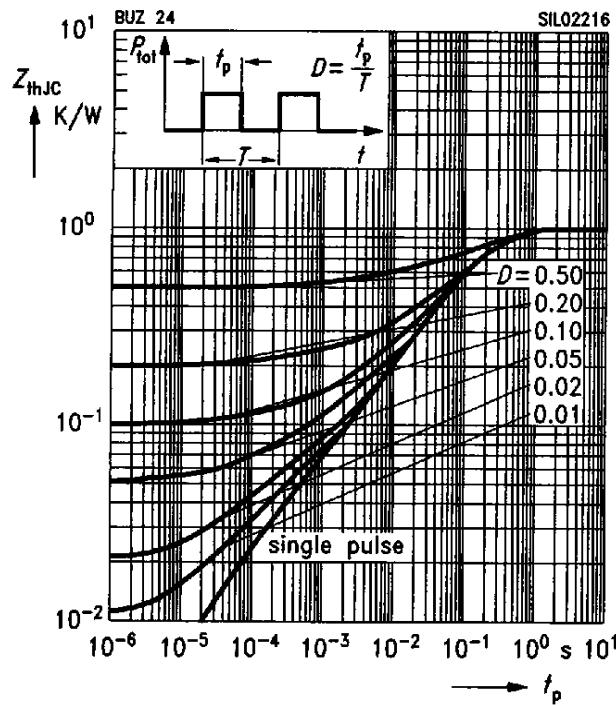
$R_{GS} = 25 \Omega$, $L = 322 \mu\text{H}$



Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

parameter: $D = t_p / T$



Typ. gate charge

$$V_{GS} = f(Q_{Gate})$$

parameter: $I_{D\ puls} = 51.0$ A

